

10/695,026

L Number	Hits	Search Text	DB	Time stamp
1	1861	(epoxy same (silica and anhydride)) and @ad<20000222	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/25 17:50
2	203	((epoxy same (silica and anhydride)) and @ad<20000222) and encapsula\$4 and (semiconductor IC (integrated adj circuit) die dice chip transistor FET)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/25 17:56
3	0	((epoxy same (silica and anhydride)) and @ad<20000222) and encapsula\$4 and (semiconductor IC (integrated adj circuit) die dice chip transistor FET)) and (MEMS micromechanical)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/25 17:56
4	38	((epoxy same (silica and anhydride)) and @ad<20000222) and encapsula\$4 and (semiconductor IC (integrated adj circuit) die dice chip transistor FET)) and (flip adj chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/25 18:15
5	960	(MEMS micromechanical) and ((transparent glass) near8 (lid cover plate)) and @ad<20000222	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/25 18:16
6	103	((MEMS micromechanical) and ((transparent glass) near8 (lid cover plate)) same (adhesive adher\$3)) and @ad<20000222	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/25 18:17
-	2	("5936758").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/25 16:26
-	199	berezny-nema.xa.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/25 16:29
-	8	berezny-nema.xa. and (texas adj instruments).as.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/25 17:49